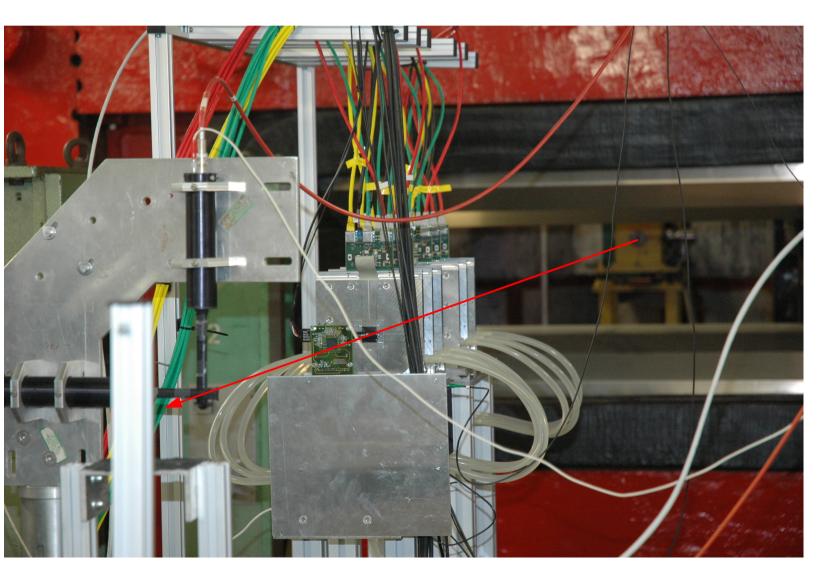
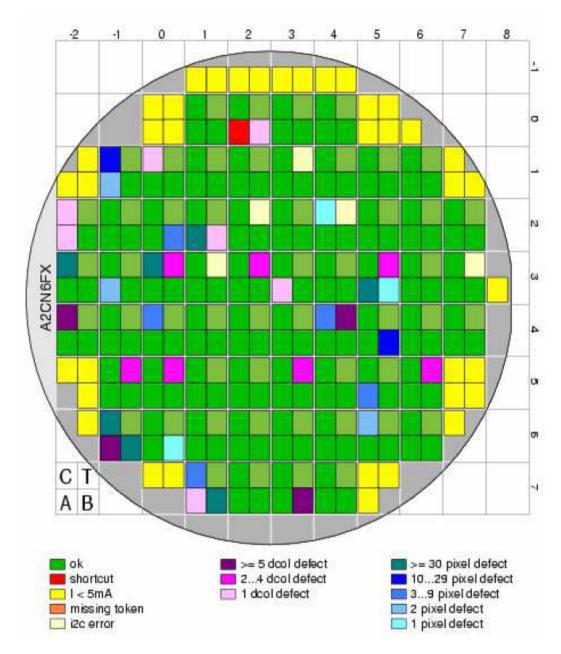
Pixel test plans

Daniel Pitzl, DESY Pixel upgrade, 15.11.2011



- schedule
- beam test
- lab tests
- X-ray test

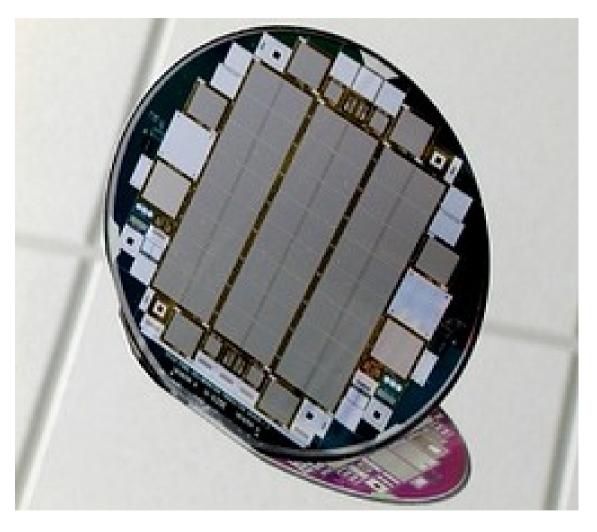
CMS Pixel ROC



Hans-Christian Kästli, Beat Meier (PSI)

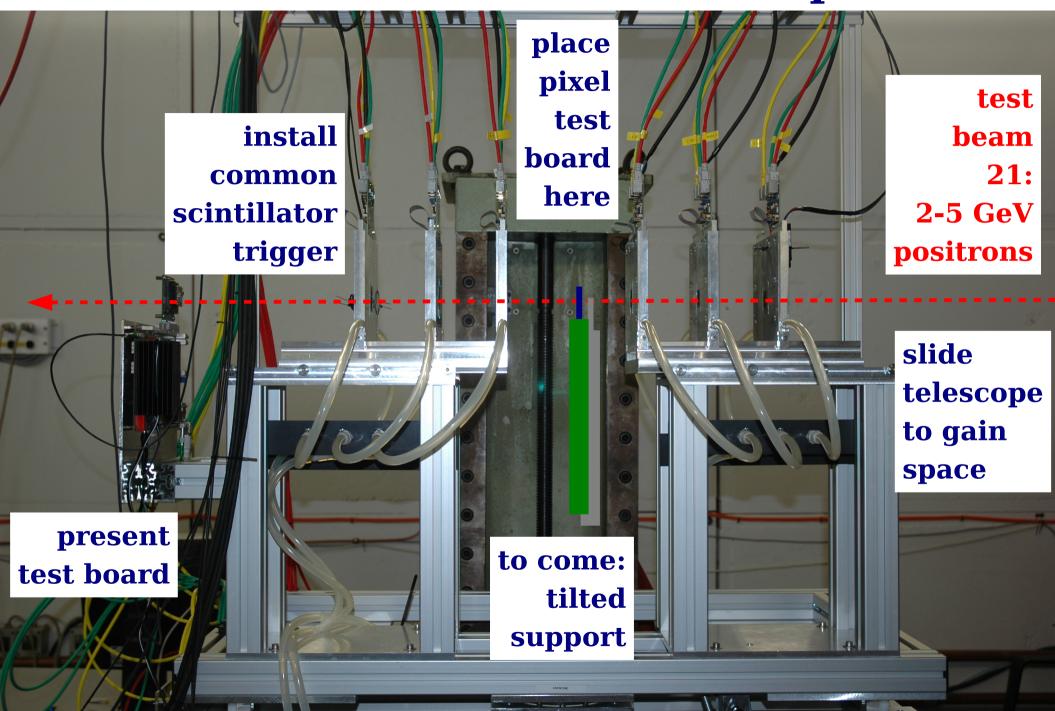
- Produced by IBM on 200 mm wafers.
- 64 recticles / wafer.
- per recticle:
 - PSI46xdb (ready)
 - PSI46dig (ready)
 - ► TBM (mid Dec)
- CMS will get 6 wafers.
- 4 months production time
- Expected in April 2012.
- Test in lab, beam, X-ray.

CMS Pixel Sensors



- 60 wafers under production at CIS (Erfurt)
 - standard CMS pixel sensor design (double sided, n-in-n, p-spray insulation).
 - for Karlsruhe, INFN, CERN/Taiwan, MRI, Purdue, DESY.
 - 5 wafers with increased bump pad passivation opening: 30 μm, for DESY.
 - ▶ Delivery in Feb 2012.
- Full sensors for first bump bondings.
- Single chip sensors for tests with new ROCs.

CMS Pixel with EuTelescope



Test beam

• this year:

analyse data

- ▶ software installed (ILCsoft: Marlin, LCIO, Millepede...) Daniel, Armin
- common scintillator trigger

Daniel, Hanno, Shiraz, Armin, Luigi

take take: CMS pixel + telescope

Daniel, Shiraz, Armin, Luigi

design and build tilting support

Adam Zuber, Holger Maser

take data at various angle of incidence

Daniel, Thomas

Hanno, Daniel

- implement broken line track fit
- https://wiki.terascale.de/index.php/GeneralBrokenLines (C.Kleinwort, V.Blobel)
- 2012:
 - prepare for new readout chip (PSI46xdb)

Daniel, Alexey, Shiraz

take data with new readout chip

Armin

all

all

study efficiency

Luigi

study resolution

DESY test beam: proposal

Beam	Responsible		Ju	ıly			Αι	ıgus	st		Se	oten	nbei	1	October					November					December				
	Collaboration/Subdetector	04	11	18	25	01	08	15	22	29	05	12	19	26	03	10	17	24	31	07	14	21	28	05	12	19	26		
All	NO BEAM																												
	July/Aug. FIXED																												
21	Gregor Telescope							П	Ш	П	П	I	Ш				П	Ш	П	П		Ш		Ш	П	IJ			
21	Garutti/Terwort CALICE																												
21	Jeans CALICE/SiW ECAL																									Г			
21	Gregor Summer Student																												
21	Eckstein CMS																												

Beam	Responsible	January					Fe	brua	ary		N	/larc	h	April				May					June			
	Collaboration/Subdetector		09	16	23		06		20		05	12					23		07	14	21	28	04	11	18	25
ALL	NO BEAM																									
	To be confirmed																									
21	Garutti																									
	CALICE																									Ш
	Weingarten			١																						
	ATLAS/PPS,IBL,3d,Dia														╙											Ш
21	Vos			1																						
	DEPFET/APD					_				_	_			_	┞			_		_	_				_	\sqcup
21	Pitzl			1																					<u> </u>	
	CMS Pixel					├		_	<u> </u>	_			<u> </u>	_	├							_	_			\longrightarrow
21				1																						

http://adweb.desy.de/~testbeam/

testing procedures

- chip testing in the lab:
 - determine operation parameters for new chips

well advanced

bare module test with probe card

to be done

stand-alone source and test beam

established

- efficiency:
 - ► pixel w.r.t. to telescope

to be done

eff(x,y,dac) = hits / tracks

to be done

- resolution:
 - pixel residuals w.r.t. telescope tracks

to be done

low temperature testing:

cold box being designed

• X-ray test

Uni HH

PSI46 test board at DESY

PSI46 chip

other adapters available

scope

600 V bias

ADC

CMS-PIXEL PSI46

Cyclone

FPGA

Cyclone

Interval Cyclone

Cyclone

Interval Cyclone

Cyclone

Interval Cyclone

Cyclone

Interval Cy

6 V power load FPGA trigger

USB1 to laptop